

# Integrated chip package structure using silicon substrate and method of manufacturing the same

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

## RESPONSE TO NON-FINAL OFFICE ACTION

5 Sir:

In response to the Office action of July 13, 2007, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

10 **Remarks/Arguments** begin on page 10 of this paper.